



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



# 2SC2631

## Silicon NPN epitaxial planar type

For low-frequency high breakdown voltage amplification  
Complementary to 2SA1123

### ■ Features

- Satisfactory linearity of forward current transfer ratio  $h_{FE}$
- High collector-emitter voltage (Base open)  $V_{CEO}$
- Small collector output capacitance (Common base, input open circuited)  $C_{ob}$

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	150	V
Collector-emitter voltage (Base open)	$V_{CEO}$	150	V
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V
Collector current	$I_C$	50	mA
Peak collector current	$I_{CP}$	100	mA
Collector power dissipation	$P_C$	750	mW
Junction temperature	$T_J$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

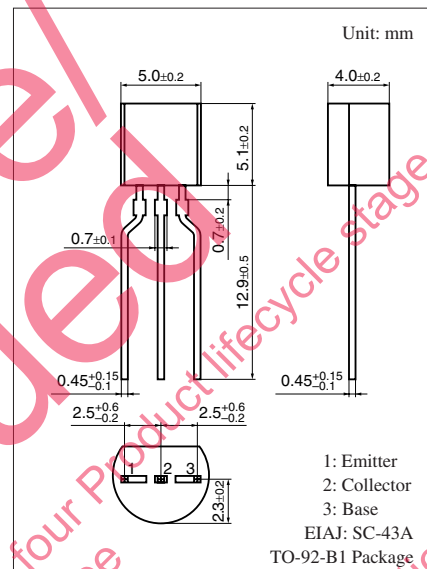
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

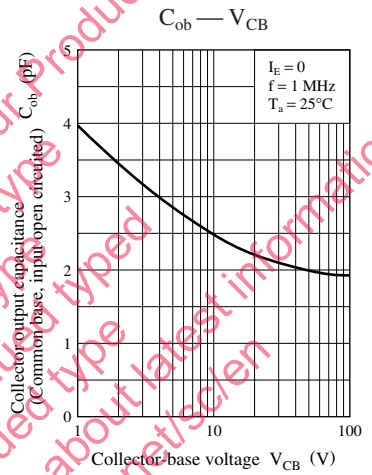
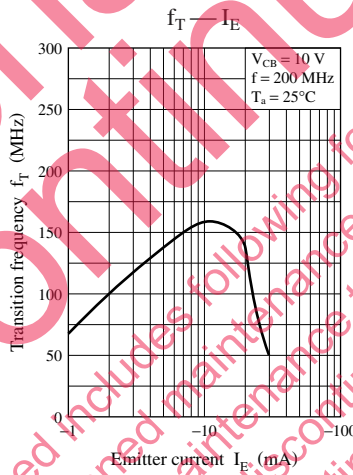
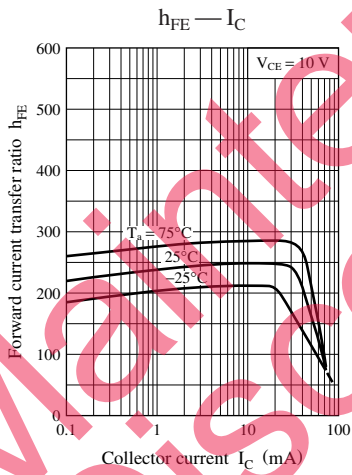
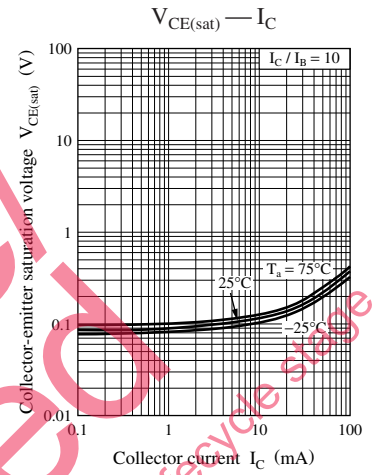
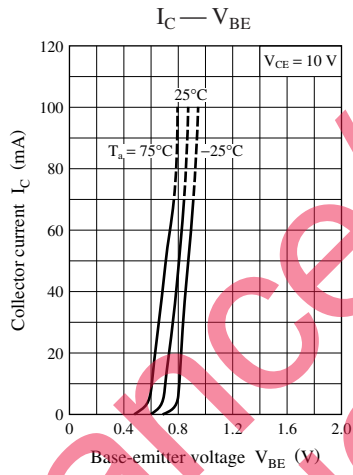
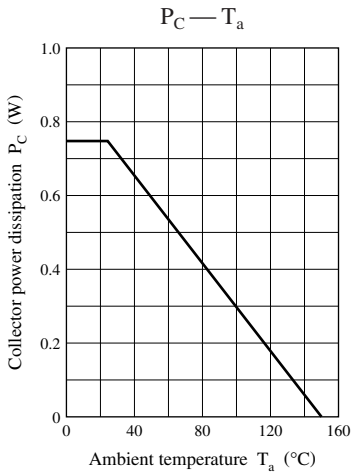
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = 100 \mu\text{A}, I_B = 0$	150			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \mu\text{A}, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 100 \text{V}, I_E = 0$			1	$\mu\text{A}$
Forward current transfer ratio *	$h_{FE}$	$V_{CE} = 5 \text{V}, I_C = 10 \text{mA}$	130		330	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 30 \text{mA}, I_B = 3 \text{mA}$			1	V
Transition frequency	$f_T$	$V_{CB} = 10 \text{V}, I_E = -10 \text{mA}, f = 200 \text{MHz}$		160		MHz
Collector output capacitance (Common base, input open circuited)	$C_{ob}$	$V_{CB} = 10 \text{V}, I_E = 0, f = 1 \text{MHz}$			3	pF
Noise voltage	NV	$V_{CE} = 10 \text{V}, I_C = 1 \text{mA}, G_V = 80 \text{dB}$ $R_{gB} = 100 \text{k}\Omega, \text{Function} = \text{FLAT}$		150	300	mV

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*: Rank classification

Rank	R	S
$h_{FE}$	130 to 220	185 to 330





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